AN-1956 LM5001 Boost Evaluation Board

User's Guide



Literature Number: SNVA393A March 2009-Revised August 2012



Contents

1	Introdu	iction5				
2	Schem	atic 6				
3	Powering and Loading Considerations					
	3.1	PROPER CONNECTIONS				
	3.2	SOURCE POWER				
	3.3	LOADING				
	3.4	OVER CURRENT PROTECTION 7				
4	Performance Characteristics					
5	Bill of Materials					
6	Printed Circuit Layout					



www.ti.com

List of Figures

1	Typical Evaluation Setup	7
2	Output Voltage During Typical Startup	8
3	Transient Response	8
4	Typical Output Ripple	9
5	Power Efficiency	9
6	Small Signal Closed Loop Response	10
7	Silkscreen Layer	11
8	Top Layer	11
9	Bottom Laver	11



AN-1956 LM5001 Boost Evaluation Board

The LM5001 boost evaluation board is designed to provide the design engineer with a fully functional power converter based on the boost topology to evaluate the LM5001 high voltage switch mode regulator.



www.ti.com Introduction

1 Introduction

The LM5001 boost evaluation board is designed to provide the design engineer with a fully functional power converter based on the boost topology to evaluate the LM5001 high voltage switch mode regulator.

The performance of the evaluation board is as follows:

Input Operating Range: 16 to 36V

Output Voltage: 48V

Output Current: 0 to 150 mA

Measured Efficiency: 91% @ 150 mA, 86% @ 75 mA

Frequency of Operation: 240 kHz Board Size: 1.75 X 1.75 inches

Load Regulation: 1% Line Regulation: 0.1%

The printed circuit board consists of 2 layers; 1 ounce copper layers FR4 material with a total thickness of

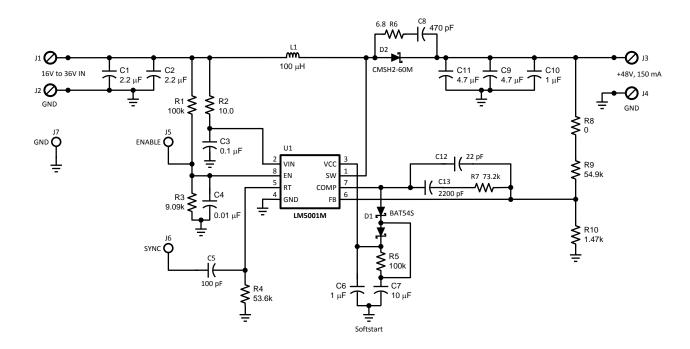
0.062 inches.

When laying out the PCB note the proximity of the ground pin (pin 4) to the output capacitors (see artwork below). Placing the ground pin near the output capacitor will minimize the ripple in the output by forcing a constant current to flow across the board for both the switch on and switch off portions of the cycle. If the board is laid out with the ground pin near the input capacitor then a high di/dt condition will occur due to the small conduction loop area during the switch on time and large loop conduction area during the switch off time. The output ripple and noise will be minimized if the conduction loop area and current both remain constant. Placing the ground pin near the output capacitor accomplishes this goal.



Schematic www.ti.com

2 Schematic



3 Powering and Loading Considerations

When applying power to the LM5001 Boost evaluation board certain precautions need to be followed. A misconnection can damage the board.

3.1 PROPER CONNECTIONS

When operated at low input voltages the evaluation board can draw up to 500mA of current at full load. The maximum rated output current is 150mA. Be sure to choose the correct connector and wire size when attaching the source supply and the load. Monitor the current into and out of the evaluation board. Monitor the voltage directly at the output terminals of the evaluation board. The voltage drop across the load connecting wires will give inaccurate measurements. This is especially true for accurate efficiency measurements. When measuring output ripple with an oscilloscope. Do not use the wire ground lead for the ground connection. The loop formed by the wire lead will pick up noise from the switching circuits and make the ripple voltage look larger then it actually is. Instead use a spring ground clip on the exposed ground ring on the scope probe to minimize the loop area of the ground lead. An alternative is to remove the shroud covering the scope probe. Then touch the exposed scope probe ground connection to the output ground terminal while simultaneously connecting the probe tip to the output terminal.



3.2 SOURCE POWER

The power supply and cabling must look like a low impedance voltage source to the evaluation board. High inductance power supply leads like the type typically used for bench power supplies, could cause the LM5001 to become unstable or have poor response to load transients. This is due to the inductance of the power supply wiring interacting with the evaluation board input capacitor and causing a series resonant LC oscillation at a frequency defined by the inductance of the input wiring and the value of the input capacitor. In some cases it may be necessary to add an additional capacitor in parallel with input capacitor to move the resonate frequency away from the unity gain crossover frequency of the LM5001. Twisting the input supply lines together will reduce the inductance and potential for problems. Powering up at max rated voltage or close to this voltage can cause damage due to the inductance of the supply lines. Over shoot and ringing can be several volts under a sudden application of power. When operating near maximum input voltage slowly ramp up the voltage to avoid overshoot.

3.3 LOADING

An appropriate electronic load, with specified operation up to 48V maximum or more, is desirable. Monitor both current and voltage at all times. Ensure there is sufficient cooling provided for the load.

3.4 OVER CURRENT PROTECTION

The LM5001 monitors the peak current through the inductor on a cycle by cycle basis. If the inductor is sized large enough to not saturate when operating at peak current limit. Then the short circuit can be left on indefinitely with out damaging the device or causing it to go into thermal shutdown.

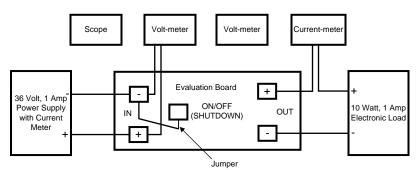


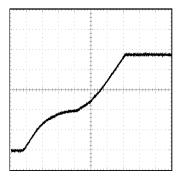
Figure 1. Typical Evaluation Setup



4 Performance Characteristics

TURN-ON WAVEFORMS

Figure 2 shows the output voltage during a typical start-up with a 20V input and a load of 150 mA. There is no overshoot during startup.



Conditions:

Input Voltage = 20VDC
Output Current = 150 mA
Trace 1:
Output Voltage
Volts/div = 10V
Horizontal Resolution = 4.0 ms/div

Figure 2. Output Voltage During Typical Startup

OUTPUT RIPPLE WAVEFORMS

Figure 3 shows the transient response for a load of change from 15 mA to 150 mA. The upper trace shows minimal output voltage droop and overshoot during the sudden change in output current shown by the lower trace.



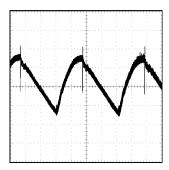
Conditions:

Input Voltage = 20VDC
Output Current = 15 mA to 150 mA
Upper Trace:
Output Voltage
Volts/div = 500 mV
Lower Trace:
Output Current
150 mA to 15 mA to 150 mA
Horizontal Resolution = 0.4 ms/div

Figure 3. Transient Response

Figure 4 shows typical output ripple seen directly across the output capacitor, for an input voltage of 20V and a load of 150 mA. This waveform is typical of most loads and input voltages.



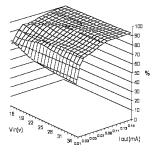


Conditions:

Input Voltage = 20VDC
Output Current = 150 mA
Bandwidth Limit = 20 MHz
Trace 1:
Output Voltage
Volts/div = 20 mV
Horizontal Resolution = 1 µs/div

Figure 4. Typical Output Ripple

Figure 5 shows power efficiency over full input voltage and output current range. Peak efficiency is at full rated load and is greater then 90% across the input voltage range.



Conditions:

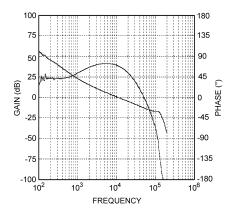
Input Voltage = 16 - 36VDC Output Current = 10 mA - 150 mA

Figure 5. Power Efficiency

Figure 6 shows the small signal closed loop response with 20V input and 150 mA load current into a resistive load. The gain curve starts at around 60dB the phase curve starts at around 45°. 0dB of crossover frequency is at 11 kHz with a phase margin of 70°.



Bill of Materials www.ti.com



Conditions:

Input Voltage = 20VDC Output Current = 150 mA

Figure 6. Small Signal Closed Loop Response

5 Bill of Materials

Designator	Qty	Part Number	Description	Value
C1, C2	2	GRM31CR71H225KA88L	CAPACITOR, 1206 X7R CER, Murata	2.2µF, 50V
C3	1	C2012X7R1H104M	CAPACITOR, 0805 X7R CER, TDK	0.1μF, 50V
C4	1	C2012X7R1H103M	CAPACITOR, 0805 X7R CER, TDK	0.01µF, 50V
C5	1	C2012COG1H101J	CAPACITOR, 0805 COG CER, TDK	100pF, 50V
C6	1	C3216X7R1C105K	CAPACITOR, 0805 X7R CER, TDK	1μF, 16V
C7	1	GRM21BR61C106KE15L	CAPACITOR, 0805 X7R CER, Murata	10μF, 16V
C8	1	C2012COG1H471J	CAPACITOR, 0805 COG CER, TDK	470pF, 100V
C9, C11	2	C5750X7R2A475M	CAPACITOR, 2220 X7R CER, TDK	4.7µF, 100V
C10	1	C3225X7R2A105K	CAPACITOR, 1210 X7R CER, TDK	1μF, 100V
C12	1	C2012COG1H220J	CAPACITOR, 0805 COG CER, TDK	22pF, 50V
C13	1	C2012COG1H222J	CAPACITOR, 0805 COG CER, TDK	2200pF, 50V
D1	1	BAT54S	DIODE, SOT-23, DUAL, SCHOTTKY, Fairchild Semiconductor	200mA, 30V
D2		CMSH2-60M	DIODE, SMA, SCHOTTKY, Central Semiconductor Corp.	2A, 60V
L1	1	MSS1260	INDUCTOR, COILCRAFT	100μH, 1.8A
R1, R5	2	CRCW08051003F	RESISTOR, 0805, VISHAY	100K
R2	1	CRCW080510R0F	RESISTOR, 0805, VISHAY	10
R3	1	CRCW08059091F	RESISTOR, 0805, VISHAY	9.09K
R4	1	CRCW08055362F	RESISTOR, 0805, VISHAY	53.6K
R6	1	CRCW080568R1F	RESISTOR, 0805, VISHAY	6.8
R7	1	CRCW08057322F	RESISTOR, 0805, VISHAY	73.2K
R8	1	CRCW08050000F	RESISTOR, 0805, VISHAY	0
R9	1	CRCW08055492F	RESISTOR, 0805, VISHAY	54.9K
R10		CRCW08051471F	RESISTOR, 0805, VISHAY	1.47K
J1, J2, J3, J4	4	7693	Keystone Screw Terminal (www.keyelco.com)	
J5, J6, J7	Mar-36	PTC36SAAN	0.025" Sq post, 36 position, Sullins	3 posts used
U1	1	LM5001M	High Voltage Switch Mode Regulator, National Semiconductor	



www.ti.com Printed Circuit Layout

6 Printed Circuit Layout

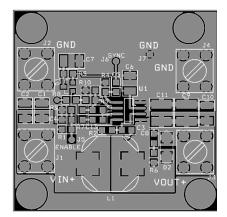


Figure 7. Silkscreen Layer

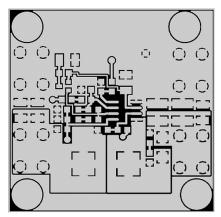


Figure 8. Top Layer

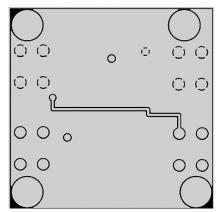


Figure 9. Bottom Layer

IMPORTANT NOTICE

Texas Instruments Incorporated and its subsidiaries (TI) reserve the right to make corrections, enhancements, improvements and other changes to its semiconductor products and services per JESD46, latest issue, and to discontinue any product or service per JESD48, latest issue. Buyers should obtain the latest relevant information before placing orders and should verify that such information is current and complete. All semiconductor products (also referred to herein as "components") are sold subject to TI's terms and conditions of sale supplied at the time of order acknowledgment.

TI warrants performance of its components to the specifications applicable at the time of sale, in accordance with the warranty in TI's terms and conditions of sale of semiconductor products. Testing and other quality control techniques are used to the extent TI deems necessary to support this warranty. Except where mandated by applicable law, testing of all parameters of each component is not necessarily performed.

TI assumes no liability for applications assistance or the design of Buyers' products. Buyers are responsible for their products and applications using TI components. To minimize the risks associated with Buyers' products and applications, Buyers should provide adequate design and operating safeguards.

TI does not warrant or represent that any license, either express or implied, is granted under any patent right, copyright, mask work right, or other intellectual property right relating to any combination, machine, or process in which TI components or services are used. Information published by TI regarding third-party products or services does not constitute a license to use such products or services or a warranty or endorsement thereof. Use of such information may require a license from a third party under the patents or other intellectual property of the third party, or a license from TI under the patents or other intellectual property of TI.

Reproduction of significant portions of TI information in TI data books or data sheets is permissible only if reproduction is without alteration and is accompanied by all associated warranties, conditions, limitations, and notices. TI is not responsible or liable for such altered documentation. Information of third parties may be subject to additional restrictions.

Resale of TI components or services with statements different from or beyond the parameters stated by TI for that component or service voids all express and any implied warranties for the associated TI component or service and is an unfair and deceptive business practice. TI is not responsible or liable for any such statements.

Buyer acknowledges and agrees that it is solely responsible for compliance with all legal, regulatory and safety-related requirements concerning its products, and any use of TI components in its applications, notwithstanding any applications-related information or support that may be provided by TI. Buyer represents and agrees that it has all the necessary expertise to create and implement safeguards which anticipate dangerous consequences of failures, monitor failures and their consequences, lessen the likelihood of failures that might cause harm and take appropriate remedial actions. Buyer will fully indemnify TI and its representatives against any damages arising out of the use of any TI components in safety-critical applications.

In some cases, TI components may be promoted specifically to facilitate safety-related applications. With such components, TI's goal is to help enable customers to design and create their own end-product solutions that meet applicable functional safety standards and requirements. Nonetheless, such components are subject to these terms.

No TI components are authorized for use in FDA Class III (or similar life-critical medical equipment) unless authorized officers of the parties have executed a special agreement specifically governing such use.

Only those TI components which TI has specifically designated as military grade or "enhanced plastic" are designed and intended for use in military/aerospace applications or environments. Buyer acknowledges and agrees that any military or aerospace use of TI components which have *not* been so designated is solely at the Buyer's risk, and that Buyer is solely responsible for compliance with all legal and regulatory requirements in connection with such use.

TI has specifically designated certain components which meet ISO/TS16949 requirements, mainly for automotive use. Components which have not been so designated are neither designed nor intended for automotive use; and TI will not be responsible for any failure of such components to meet such requirements.

Products Applications

Audio Automotive and Transportation www.ti.com/automotive www.ti.com/audio **Amplifiers** amplifier.ti.com Communications and Telecom www.ti.com/communications **Data Converters** dataconverter.ti.com Computers and Peripherals www.ti.com/computers DI P® Products Consumer Electronics www.dlp.com www.ti.com/consumer-apps

DSP dsp.ti.com **Energy and Lighting** www.ti.com/energy Clocks and Timers www.ti.com/clocks Industrial www.ti.com/industrial Interface Medical www.ti.com/medical interface.ti.com Logic logic.ti.com Security www.ti.com/security

Power Mgmt <u>power.ti.com</u> Space, Avionics and Defense <u>www.ti.com/space-avionics-defense</u>

Microcontrollers microcontroller.ti.com Video and Imaging www.ti.com/video

RFID www.ti-rfid.com

OMAP Applications Processors www.ti.com/omap TI E2E Community e2e.ti.com

Wireless Connectivity <u>www.ti.com/wirelessconnectivity</u>